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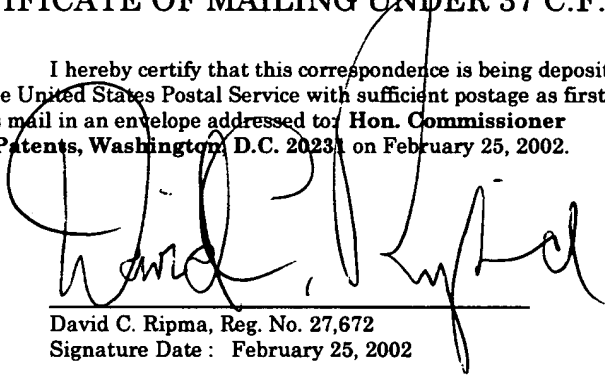
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of) PATENT APPLICATION
Inventor: Wei Pan, Yoshi Ono, David)
R. Evans, and Sheng Teng Hsu)
Serial No.: 09/819,296) ATTORNEY DOCKET
Filed: March 27, 2001) No. SLA0515
Title: MULTI-LAYERED BARRIER)
METAL THIN FILMS FOR)
Cu INTERCONNECT BY)
ALCVD)

#3/Election
4/6/02
✓

CERTIFICATE OF MAILING UNDER 37 C.F.R. § 1.8

I hereby certify that this correspondence is being deposited
in the United States Postal Service with sufficient postage as first
class mail in an envelope addressed to: **Hon. Commissioner**
for Patents, Washington, D.C. 20231 on February 25, 2002.


David C. Ripma, Reg. No. 27,672
Signature Date : February 25, 2002

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RESPONSE TO RESTRICTION REQUIREMENT

Hon. Commissioner for Patents
Washington, D.C. 20231

Sir:

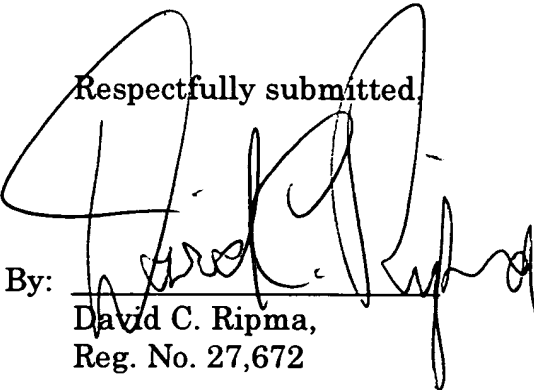
This communication responds to an Office Action dated
February 15, 2002 in the above-identified patent application. In the Office
Action the Examiner requires restriction to one of the following
inventions:

Group I. Claims 1-7, drawn to a device; and

Group II. Claims 8-20, drawn to a method.

Applicants hereby elect to pursue the Group II claims, claims
8-20, drawn to a method.

Date: Feb. 25, 2002

Respectfully submitted,

By: David C. Ripma,
Reg. No. 27,672

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